

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2680	235/492.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:03
L2	391	1 and laminat\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:03
L3	39	2 and elastic	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:03
L4	11	2 and (elastic same (bond\$4 or adhe\$5))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:04
L5	163	2 and (bend\$4 or stress)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:04
L6	38	5 and battery	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 13:04
S1	5720818	DE "102" "26" "848" A1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/15 13:10
S2	0	DE10226848A1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 06:44
S3	3	"10226848"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 07:33
S4	124	WOEHRLE.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 06:45
S5	20	WOEHRLE.in. and VARTA.as.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 06:45
S6	1	DE10102125	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:11

S7	108	galvan\$4 same IC	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:11
S8	8	galvan\$4 same IC same lithium	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:16
S9	209773	lithium	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:16
S10	25621	lithium same electrode\$1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:17
S11	61	lithium same electrode\$1 same card\$1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 08:17
S12	1205	galvanic\$4 same film\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:13
S13	227	galvanic same films	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:13
S14	48	S13 and laminat\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:13
S15	4	S13 and iso	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:13
S17	5	((chip or smart or ic or credit) adj1 card) same galvanic\$4 same (recess\$4 or cavit\$4 or hole\$1)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:18
S18	1	((chip or smart or ic or credit) adj1 card) same galvanic\$4 same (recess\$4 or cavit\$4 or hole\$1) same core	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:18
S19	1	card\$1 same galvanic\$4 same (recess\$4 or cavit\$4 or hole\$1) same core	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 19:19

S20	108	card\$1 and galvanic\$4 and (recess\$4 or cavit\$4 or hole\$1) and core	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 13:45
S21	40	card\$1 and galvanic\$4 and (recess\$4 or cavit\$4 or hole\$1) and core same (batter\$4 or energy)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 08:53
S22	34	battery near40 mount\$4 near40 (recess\$4 or cavit\$4) near40 (core\$1 or layer\$1 or substrate\$1)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 09:14
S23	294	battery same mount\$4 same (recess\$4 or cavit\$4) same (core\$1 or layer\$1 or substrate\$1)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 19:55
S24	1	galvan\$4 same lithium\$4 same card	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 09:10
S25	0	S23 and S24	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 08:56
S26	7	galvan\$4 same lithium\$4 and card	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 08:56
S27	0	S23 and S26	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 08:56
S28	65	((chip or smart or ic or credit) adj1 card) same galvanic\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 09:17
S29	1	"6077106".pn. and batter\$4 and mount\$4 and card\$4 and substrat\$4 and cavit\$4 and memor\$4 and contact\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 09:44
S30	148	battery same (recess\$4 or cavit\$4) same (core\$1 or layer\$1 or substrate\$1) same (adhe\$5 or bond or glue)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 19:56
S31	12	battery same (recess\$4 or cavit\$4) same (core\$1 or layer\$1 or substrate\$1) same (adhe\$5 or bond or glue) same card\$1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 19:56

S32	502	card\$1 same core same adhe\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 13:46
S33	131	card\$1 same core same adhe\$4 same applied	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 13:50
S34	22	card\$1 same core same adhe\$4 same applied same (recess or cavit\$4 or hole\$1)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 13:50
S35	370	card\$4 same core near30 (adhe\$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/15 15:24
S36	81	card\$4 same core same (adhe\$4) same (layer\$1 or sheet\$1) same (cavit\$4 or hole\$1 or recess\$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/15 16:04
S37	0	card\$4 same core same (adhe\$4) same (layer\$1 or sheet\$1) same (cavit\$4 or hole\$1 or recess\$4) same cold same laminat\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/15 16:04
S38	14	card\$4 same core same (adhe\$4) same (layer\$1 or sheet\$1) same (cavit\$4 or hole\$1 or recess\$4) same laminat\$4 not heat	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/15 17:40
S39	14	card\$4 same core same (adhe\$4) same (layer\$1 or sheet\$1) same laminat\$4 same room	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:05
S40	94	card\$4 same (layer\$1 or sheet\$1) same laminat\$4 same (room or cold) same temperature	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:06
S41	21	card\$4 same (layer\$1 or sheet\$1) same laminat\$4 same (room or cold) same temperature same core\$1	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:06
S42	2989	235/492,488.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:27
S43	14	S40 and S42	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:26

S44	8	S41 and S42	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/18 14:26
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